

FORMING A CHIP PACKAGE  
HAVING A NO-FLOW UNDERFILL

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ABSTRACT OF THE DISCLOSURE

10 A method of forming an underfilled chip package is  
provided. No-flow underfill material is deposited over a  
surface of a package substrate to form an underfill  
region. A die having a plurality of solder bumps is  
placed at an angle relative to the package substrate such  
that solder bumps adjacent a first side of the die  
contact the surface of the package substrate within the  
underfill region while solder bumps adjacent a second  
15 side of the die are generally located at a distance away  
from the surface of the package substrate. The second  
side of the die is moved toward the surface of the  
package substrate until the solder bumps adjacent the  
second side of the die contact the surface such that the  
20 underfill material is forced into the area between the  
plurality of bumps.